

MAS9275

IC FOR 10.00 - 30.00 MHz VCXO

This is preliminary information on a new product under development.



- **Low Power**
- **Wide Supply Voltage Range**
- **Square Wave Output**
- **Very High Level of Integration**
- **Very Low Phase Noise**
- **Low Cost**

DESCRIPTION

The MAS9275 is an integrated circuit well suited to build VCXO for telecommunication application. To

build a VCXO only one additional component a crystal is needed.

FEATURES

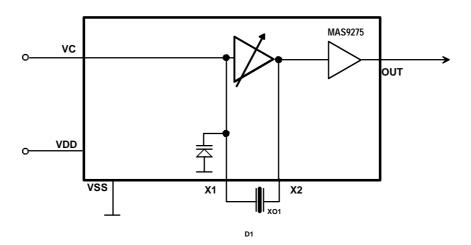
Very small size

- Minor current draw
- Wide operating temperature range
- Phase noise <-130 dBc/Hz at 1 kHz offset
- Square wave output

APPLICATIONS

- VCXO for mobile phones
- VCXO for other telecommunications systems

BLOCK DIAGRAM





PIN DESCRIPTION

| Pin Description | Symbol | x-coordinate | y-coordinate | Note |
|-----------------------------------|--------|--------------|--------------|------|
| Crystal/Varactor Oscillator Input | X1 | 209 | 209 | |
| Voltage Control Input | VC | 425 | 213 | |
| Power Supply Ground | VSS | 600 | 226 | |
| Buffer Output | OUT | 1029 | 1076 | |
| Power Supply Voltage | VDD | 371 | 1065 | |
| Crystal Oscillator Output | X2 | 197 | 1080 | |
| Tri State | PD | 830 | 1076 | 1) |

Note1: Output buffer is off during voltage in PD pin stays between 1.6 V and VDD.

Note: Because the substrate of the die is internally connected to GND, the die has to be connected to GND or left floating. Please make sure that GND is the first pad to be bonded. Pick-and-place and all component assembly are recommended to be performed in ESD protected area.

Note: Pad coordinates are measured from the left bottom corner of the chip to the center of the pads. The coordinates may vary depending on sawing width and location, however, distances between pads are accurate.

ABSOLUTE MAXIMUM RATINGS

| Parameter | Symbol | Min | Max | Unit | Note |
|---------------------|---------------------|----------------------|----------------|------|------|
| Supply Voltage | V_{DD} - V_{SS} | -0.3 | 6.0 | V | |
| Input Pin Voltage | | V _{SS} -0.3 | $V_{DD} + 0.3$ | V | |
| Power Dissipation | P _{MAX} | | 100 | mW | |
| Storage Temperature | T _{ST} | -40 | 120 | °C | |

RECOMMENDED OPERATION CONDITIONS

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|-----------------------------|-----------------|----------------------------|-----|-----|-----|--------|
| Supply Voltage | V_{DD} | | 2.7 | 2.8 | 5.5 | V |
| Supply Current | I _{dd} | VDD = 2.8 Volt | | 2.3 | | mA |
| Operating Temperature | T _{OP} | | -30 | | +85 | °C |
| Storage Temperature | T _S | Relative humidity = 15%70% | -5 | | +40 | °C |
| Crystal Pulling Sensitivity | S | | | 30 | | ppm/pF |
| Crystal Load Capacitance | C _L | | | 7 | | pF |

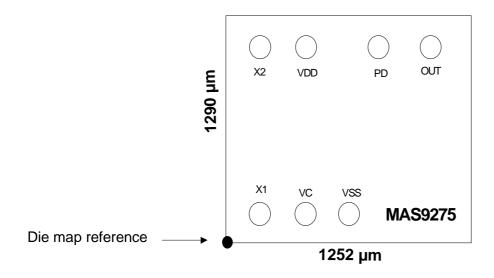


ELECTRICAL CHARACTERISTICS

| Parameter | Symbol | Min | Тур | Max | Unit | Note |
|-----------------------------------|--------------------|-------|-------|-------|-------|------|
| Frequency Range | f _o | 10.00 | | 30.00 | MHz | |
| Voltage Control Range | V _C | 0 | | VDD | V | |
| Voltage Control Sensitivity | V _{CSENS} | | 100 | | ppm/V | 1) |
| Output Voltage (10 pF, VDD 2.7 V) | V_{out} | | 2.3 | | Vpp | |
| Output Voltage (10 pF, VDD 5.0 V) | V_{out} | | 4.5 | | Vpp | |
| Rise and Fall Time (10 - 50 pF) | | | | 10 | ns | |
| Output Symmetry | | | 40-60 | | % | |
| Startup Time | T _{START} | | 2 | | ms | |

Note 1: VC sensitivity value depends on the crystal used.

IC OUTLINES

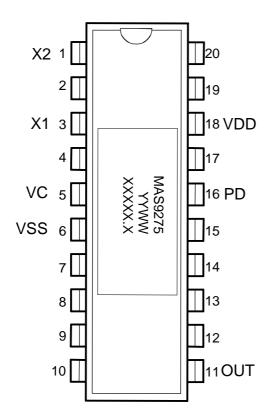


Note 1: MAS9275 pads are round with 80 µm diameter at opening.

Note 2: Die map reference is the actual left bottom corner of the sawn chip.



SAMPLES IN SB20 DIL PACKAGE



Top marking: YYWW = Year, Week XXXXX.X = Lot number



ORDERING INFORMATION

| Product Code | Product | Package | Comments |
|--------------|-------------|--------------------------|-------------------------|
| MAS9275ATC1 | IC FOR VCXO | EWS tested wafers 400 µm | Die size 1252 x 1290 μm |
| MAS9275ATG1 | IC FOR VCXO | EWS tested wafers 215 µm | Die size 1252 x 1290 μm |
| MAS9275 | IC FOR VCXO | SMD Package T.B.D. | |

Please contact Micro Analog Systems Oy for other wafer thickness options.

| LOCAL DISTRIBUTOR | | | |
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